



Click [here](#) for the 3D model.

### Dimensions

|           |                 |
|-----------|-----------------|
| Chip Size | 1808            |
| L         | 4.7mm +/-0.5mm  |
| W         | 2mm +/-0.2mm    |
| T         | 1.6mm +/-0.15mm |
| B         | 0.6mm +/-0.35mm |

### Packaging Specifications

|                    |                          |
|--------------------|--------------------------|
| Packaging          | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 1000                     |

### General Information

|                          |   |
|--------------------------|---|
| Series                   | SMD Auto COG HV   |
| Style                    | SMD Chip  |
| Description              | SMD, MLCC, Ultra-Stable, Low Loss, High Voltage, Automotive Grade |
| Features                 | Ultra-Stable, Low Loss, Automotive Grade                          |
| RoHS                     | Yes   |
| Termination              | Tin   |
| Marking                  | No  |
| Qualifications           | AEC-Q200  |
| AEC-Q200                 | Yes   |
| Typical Component Weight | 81 mg   |
| Shelf Life               | 78 Weeks  |
| MSL                      | 1   |

### Specifications

|  |                           |
|--|---------------------------|
| Capacitance  | 22 pF                     |
| Measurement Condition  | 1 MHz 1.0Vrms             |
| Capacitance Tolerance  | 10%                       |
| Voltage DC   | 3000 VDC                  |
| Dielectric Withstanding Voltage                                    | 3600 VDC                  |
| Temperature Range  | -55/+125°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade Hour       |
| Insulation Resistance  | 100 GOhms                 |